

SOT560-1

plastic thermal enhanced bottom chip carrier; 32 terminals;
body 5 x 5 x 0.65 mm

21 June 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HBCC32
Package type industry code	HBCC32
Package style descriptive code	HBCC (thermal enhanced bottom chip carrier)
Package body material type	P (plastic)
JEDEC package outline code	MO-217
Mounting method type	S (surface mount)
Issue date	12-3-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.9	-	5	5.1	mm
E	package width		4.9	-	5	5.1	mm
A	seated height		-	-	0.8	0.8	mm
A ₂	package height		0.6	-	0.65	0.7	mm
e	nominal pitch		-	-	0.5	-	mm
n ₂	actual quantity of termination		-	-	32	-	



2. Package outline

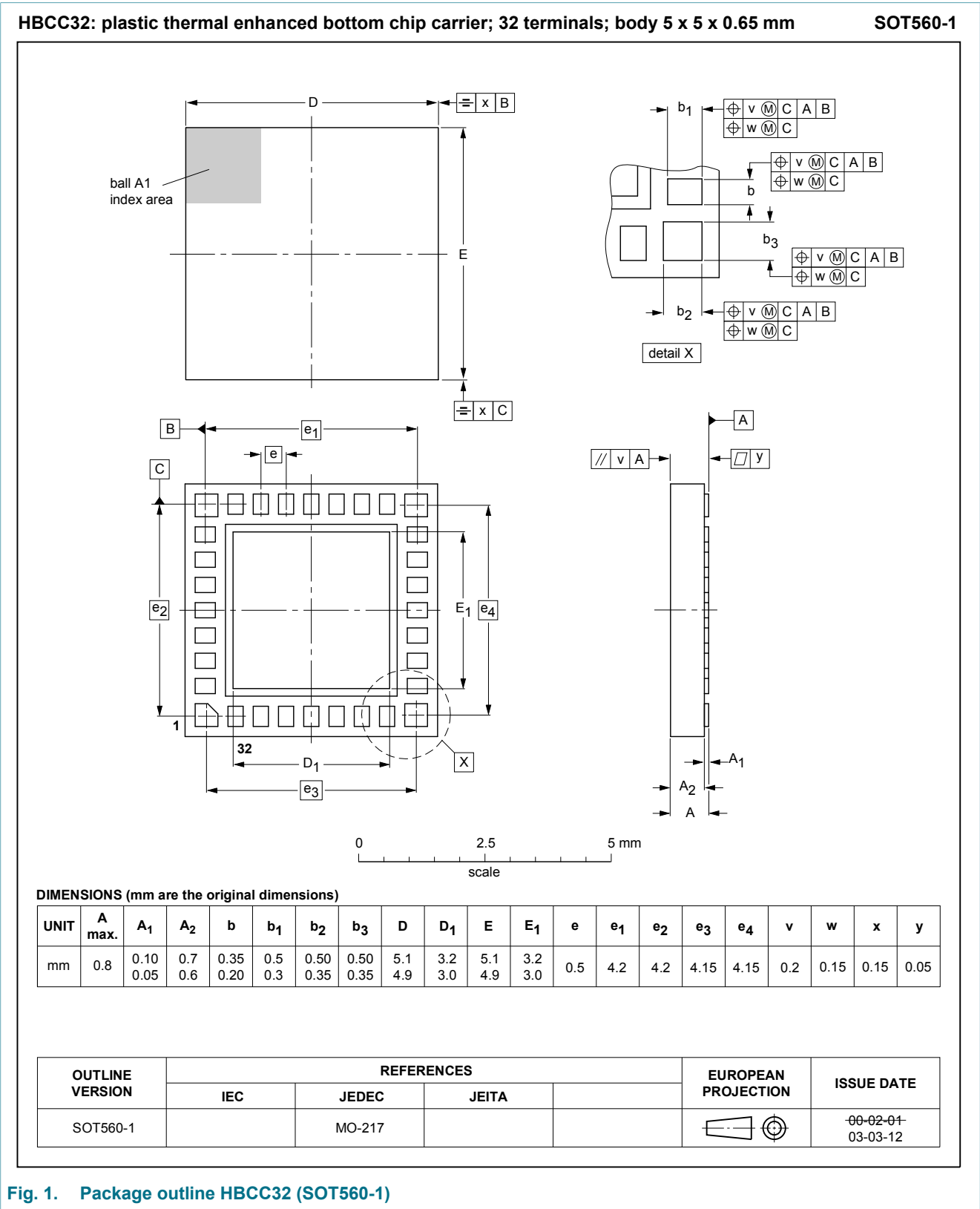


Fig. 1. Package outline HBCC32 (SOT560-1)

3. Soldering

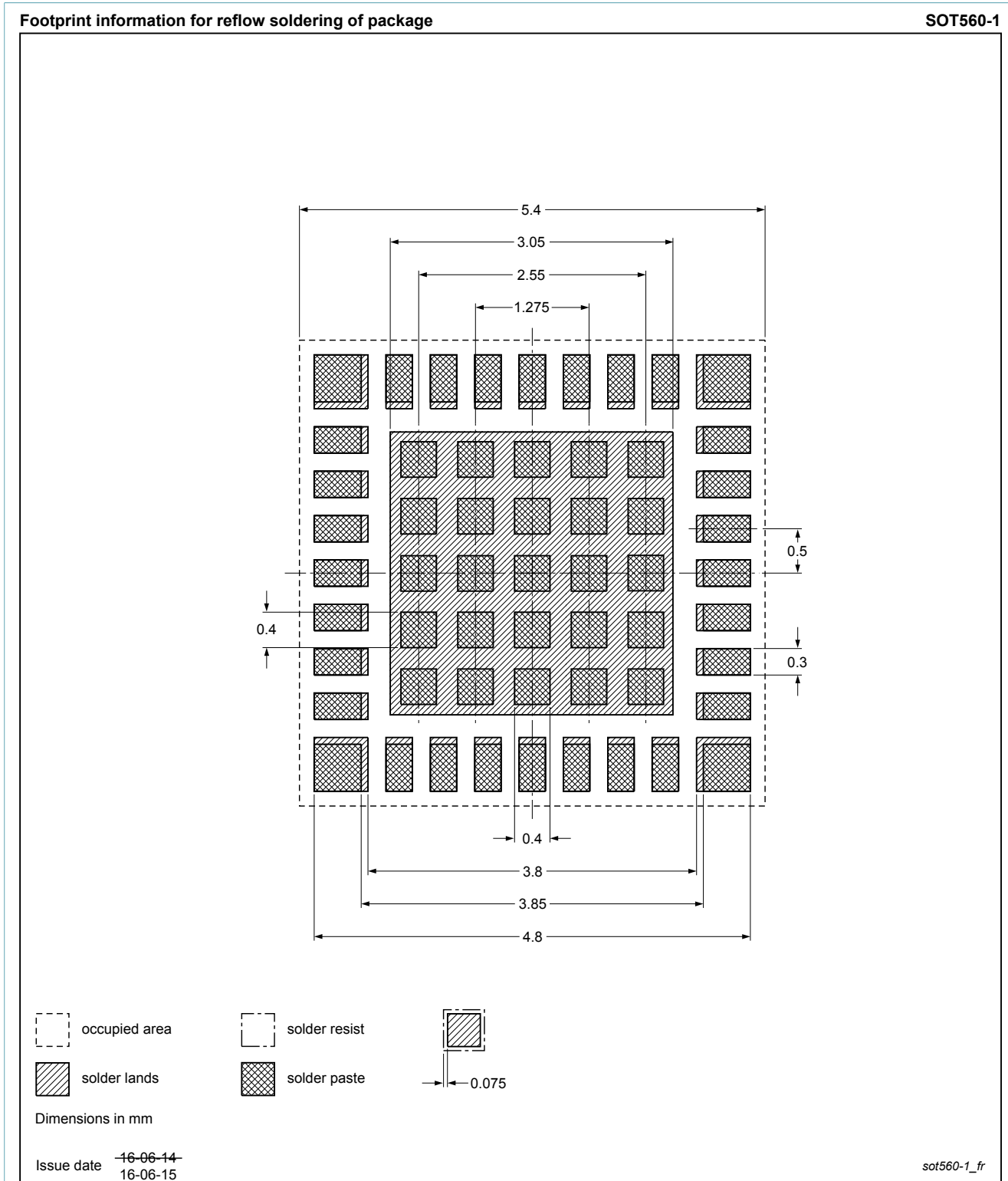


Fig. 2. Reflow soldering footprint for HBCC32 (SOT560-1)

4. Legal information

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